BERGQUIST GAP PAD TGP 5000,GAP PAD 5000S35

产品名称	BERGQUIST GAP PAD TGP 5000,GAP PAD 5000S35
公司名称	深圳市华思瑞科技有限公司
价格	50.00/PCS
规格参数	品牌:BERGQUIST 型号:GP5000S35 产地:USA
公司地址	深圳市龙岗区坂田街道中浩金裕城工业区F3栋
联系电话	0755-86652465 13798203669

产品详情

High Thermal Conductivity Plus “ S-Class ” Softness and Conformability

Features and Benefits

High-thermal conductivity: 5.0 W/m-K

Highly conformable, “ S-Class ” softness

Naturally-inherent tack reduces

interfacial thermal resistance

Conforms to demanding contours and

maintains structural integrity with little

or no stress applied to fragile

component leads

Fiberglass reinforced for puncture,

shear and tear resistance

Excellent thermal performance at

low pressures

BERGQUIST GAP PAD TGP 5000 is a fiberglass-reinforced filler and polymer featuring a high thermal conductivity. The material yields extremely soft characteristics while maintaining elasticity and conformability. The fiberglass reinforcement provides easy handling and converting, added electrical isolation and tear resistance. The inherent natural tack on both sides assists in application and allows the product to effectively fill air gaps,enhancing the overall thermal performance.The top side has reduced tack for ease of handling. BERGQUIST GP5000S35 is ideal for high-performance applications at low mounting pressures.

BERGQUIST GAP PAD 5000S35 Typical Applications Include:

Voltage Regulator Modules (VRMs) and POLs

CD-ROMs and DVD-ROMs

PC Board to chassis

ASICs and DSPs

Memory packages and modules

Thermally-enhanced BGAs

Configurations Available:

Die-cut parts are available in any shape or size, separated or in sheet form